

Japan Packaging Committee Meeting Summary and Minutes

SEMICON Japan 2012
Thursday, December 6, 2012, 12:30-14:00
Makuhari Messe, Chiba, Japan

Next Committee Meeting

SEMI Japan Standards Spring 2013 Meetings
Monday, March 25, 2013, 15:00-17:00
SEMI Japan, Tokyo, Japan

Table 1 Meeting Attendees

Co-Chairs: Kazunori Kato (AiT), Masahiro Tsuruya (iNEMI)

SEMI Staff: Naoko Tejima (SEMI Japan)

<i>Company</i>	<i>Last</i>	<i>First</i>	<i>Company</i>	<i>Last</i>	<i>First</i>
Tokyo Seimitsu	Chiba	Kiyotaka	Elpida Memory	Sonobe	Kaoru
AiT	Kato	Kazunori	Osaka University	Tabata	Haruo
Disco	Kawai	Akihito	Shin-Etsu Polymer	Tanaka	Kiyofumi
Disco	Masuchi	Sumio	iNEMI	Tsuruya	Masahiro
Lintec	Murakami	Yukinori	Miraial	Umeda	Toshiya
-	Nakamura	Kazuhiko	Lintec	Watanabe	Kenichi
Disco	Nakanishi	Yuji	Miraial	Yamamoto	Norimune
Achilles	Nishijima	Masayuki	SEMI Japan	Tejima	Naoko
Intel	Radloff	Stefan			

** alphabetical order by last name*

Table 2 Leadership Changes

<i>Group</i>	<i>Previous Leader</i>	<i>New Leader</i>
Handling and Packing Materials for Assembling Advanced Electronic Device under Clean Environment Task Force was disbanded.	Yuichi Morishita (Achilles) Taisei Murata (Gold Industries)	None

Table 3 Ballot Results

None

Table 4 Authorized Ballots

<i>#</i>	<i>When</i>	<i>SC/TF/WG</i>	<i>Details</i>
4965C	C1-13	JA 450mm Assembly & Test Die Preparation Task Force	NEW STANDARD: Mechanical Interface Specification for 450 mm Load Port for Tape Frame Cassettes in the Backend Process

Table 5 Authorized Activities

None

Table 6 New Action Items (or move to Section 8, Action Item Review)

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
PKG111125-1	Sumio Masuchi	To draft a related document for Doc.#4814A (New Standard: Specification for Tape Frame Cassette for 450 mm Wafer)
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee
PKG120829-3	All Task Force Leaders	To review the both TFOF (Charter, Scope and Members) and SNARFs (Rationale and Scope) which they themselves are involved
PKG121206-1	Japan Assembly & Test Die Preparation Task Force	To submit Doc.#4965C for Cycle 1, 2013.

1 Welcome, Reminders and Introductions

Masahiro Tsuruya, committee co-chair, called the meeting to order at 12:30. Self-introductions were made followed by the agenda review.

2 Technical Committee Award

Technical Committee Awards were given to the below member to appreciate his outstanding efforts and leadership.

- Sumio Masuchi (Disco) – 450mm ATDP Task Force activities

3 Required Meeting Elements

The meeting reminders on program membership requirement, antitrust issues, intellectual property issues and international effective meeting guidelines, were reviewed by SEMI staff, Naoko Tejima.

4 Review of Previous Meeting Minutes

The committee reviewed the minutes of the previous meeting held on August 29, 2012.

Motion: To approve the minutes of the previous meeting as written.

By / 2nd: Kiyofumi Tanaka (Shin-Etsu Polymer) / Haruo Tabata (Osaka University)

Discussion: None

Vote: 11 in favor and 0 opposed. **Motion passed.**

Attachment: 01_JA_Package_Previous_Mtg_Minutes_121206

5 SEMI Staff Report

Naoko Tejima gave the SEMI staff report. This report included SEMI Global 2012-2013 Calendar of Events, SEMICON Japan 2012, 2012 Standards Awards, 2013 Critical Dates for SEMI Standards Ballots, Regulation SC Report, A&R SC Report, SEMI Standards Publication, New Standards Ballot and Membership Systems, New Ballot Formatting Templates, Style Manual and Compilation of Terms and Contact Information.

Attachment: 02_SEMI_Staff_Report_121206

6 Liaison Reports

6.1 North America & Taiwan 3DS-IC Committee Report

Naoko Tejjima briefly reported for the North America & Taiwan 3DS-IC Committee. This report included Leadership, Organization Chart, Meeting Information, Document Review Summary, SNARFs, Upcoming NA 3DS-IC Ballots for Cycle 1, 2013 and NA 3DS-IC Spring 2013 Meeting Schedule.

Attachment: 03_NA_&_TW_3DS-IC_Report_121206

7 Task Force Reports

7.1 Japan Assembly & Test Die Preparation Task Force

Sumio Masuchi reported on progress for Japan Assembly & Test Die Preparation Task Force. Of note:

- The Task Force has completed drafting *Doc.#4965C, New Standard: Mechanical Interface Specification For 450 mm Load Port For Tape Frame Cassettes In Backend Process*, and it is almost ready to be submitted for Cycle 1, 2013.

Motion: To submit Doc.#4965C for Cycle 1, 2013

By / 2nd: Sumio Masuchi (Disco)/ Kiyofumi Tanaka (Shin-Etsu Polymer)

Discussion: None.

Vote: 12 in favor and 0 opposed. **Motion passed.**

- The Task Force has been drafting “Related Information” of “SEMI G92-0412, Specification for Tape Frame Cassette for 450 mm Wafer”. It was proposed to add the following 2 items by Stefan Radloff, just prior to this committee meeting.
 - A background statement
 - Additional information about KC pins and KC pin grooves on the carrier.

Therefore, the Task Force will discuss the above again and will propose the revised one at the next packaging committee meeting.

Action Item: The Task Force to submit Doc.#4965C for Cycle 1, 2013.

7.2 Handling and Packaging Materials for Assembling Advanced Electronic Device under Clean Environment Task Force

Instead of the Task Force leader, Kazuhiko Nakamura reported for Handling and Packaging Materials for Assembling Advanced Electronic Device under Clean Environment Task Force. Of note:

- Task force did “fact-findings” of the particulate emission by several testing methods, however, could not be found the suitable measurement method to standardize.
- The survey of ESD will be continued by the volunteers.

Motion: To disband the Handling and Packing Materials for Assembling Advanced Electronic Device under Clean Environment Task Force.

By / 2nd: Kazuhiko Nakamura (-) / Kazunori Kato (AiT)

Discussion: None

Vote: 14 in favor and 0 opposed. **Motion passed.**

Attachment: 04_Handling_&_Packaging_Materials_TF_Report_121206_(JA_only)

7.3 Electromagnetic Characterization Study Group

Naoko Tejima gave the report from Mikio Kiyono, the leader of the Electromagnetic Characterization Study Group. Kazunori Kato also added some comments as follows:

- The Electromagnetic Characterization Study Group is going to continue the activities, in conjunction with JEITA standards activities
- As the information was sent, Mikio Kiyono will make a presentation about Electromagnetic Characterization titled “Beyond 10Gb/s” at the TPSS seminar on December 13. The workshop will be also held in March together with DFM Study Group.

Attachment: 05_Electromagnetic_Characterization_SG_Report_121206_(JA_only)

7.4 Packages and Packaging Materials Eco-efficiency Task Force

Kazuhiko Nakamura reported on progress for the Packages and Packaging Materials Eco-efficiency Task Force. Of note:

- The Task Force will draft the document of “Guide for Implementation of Eco-efficiency Indicators for Semiconductor Package”, getting advices of The National Institute of Advanced Industrial Science and Technology (AIST).
- SNARF will be submitted after the next committee meeting.
- Kazunori Kato advised that the draft document should be checked by some of members of the major players before the document will be submitted for the ballot

Attachment: 06_P&PM_Eco-efficiency_TF_Report_121206_(JA_only)

7.5 Wafer Shipping Container for Assembly & Packaging Task Force

Kazuhiko Nakamura reported for the Wafer Shipping Container for Assembly & Packaging Task Force. Of note:

- *Doc. #5295, New Standard: Specification for Coin-Stack Type Tape Frame Shipping Container for 300 mm Wafer*, is currently under review at the A&R Subcommittee. When it will pass and be published without any problems, most of activities of the Task Force seems to be finished. After that, Task Force will offer to disband.

Attachment: 07_Wafer_Shipping_Container_TF_Report_121206_(JA_only)

7.6 DFM Study Group

Instead of the DFM Study Group leader, Kazunori Kato reported that the Study Group has reported as follows.

- Ichiro Anjo will make a presentation titled “New DRAM architecture and Packaging Technology” at the TPSS seminar on December 13. The workshop will be also held in March together with *Electromagnetic Characterization Study Group*.
- Study Group should be discussed the name of the present Study Group. (DFM” is suitable to the present situation? Or should be changed to what suits the present situation)

7.7 3D-IC Study Group

Masahiro Tsuruya reported on progress for the 3D-IC Study Group. The future plans, targets, and how to collaborate with NA & TW 3DS-IC Committee, will be discussed at the 3D-IC Study Group meeting in succession to this Packaging Committee Meeting.

Attachment: 08_3D-IC_SG_Report_121206

8 Old Business

8.1 Previous Meeting Action Items

Naoko Tejima reviewed the previous meeting action items.

Table 7 Previous Meeting Actions Items

<i>Item #</i>	<i>Assigned to</i>	<i>Details</i>
PKG111125-1	Sumio Masuchi	To draft a related document for Doc. 4814A (New Standard: Specification for Tape Frame Cassette for 450 mm Wafer) Open
PKG120622-2	Kazunori Kato and other co- chairs	To have a meeting with Mikio Kiyono, the leader of Electromagnetic Characterization Study Group, within July and ask him about the future plan/activities and the policy. Closed
PKG120829-1	SEMI Staff	To forward adjudication result of Doc.5295 to the ISC A&R Subcommittee for procedural review. Closed
PKG120829-2	Committee Co-Chairs	To review the Committee Charter of Japan Packaging Committee Open
PKG120829-3	All Task Force Leaders	To review the both TFOF (Charter, Scope and Members) and SNARFs (Rationale and Scope) which they themselves are involved Open
PKG120829-4	SEMI Staff	To contact with Taisei Murata, the other TF leader, and to tell him the committee's intention. Closed
PKG120829-5	Wafer Shipping Container for Assembly & Packaging Task Force	To discuss the next works by the next committee meeting. Closed
PKG120829-6	Co-leaders of 3D-IC Study Group	To suggest the activity plan of the 3D-IC Study Group as the Japan Packaging Committee by Dec. 6 (the next Committee Meeting) Closed
PKG120829-7	SEMI Staff	To send the invitation of Study Group to the Japan Packaging Committee Member and The participants of today's workshop Closed
PKG120829-8	SEMI Staff	To check the registration status of 3D-IC Study Group attendees Closed

9 New Business

None

10 Action Item Review

10.1 New Action Items

Naoko Tejima reviewed the new action items. These can be found in the New Action Items table at the beginning of these minutes.

11 Next Meeting and Adjournment

The next meeting of the Japan Packaging Committee is scheduled for Monday, March 25, 2013, 15:00-17:00, at SEMI Japan, Tokyo, Japan.



Respectfully submitted by:
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Minutes approved by:

Kazunori Kato (AiT), Co-chair	January 15, 2013
Masahiro Tsuriya (iNEMI), Co-chair	January 15, 2013

Table 8 Index of Available Attachments #1

#	Title
1	JA_Package_Previous_Mtg_Minutes_121206
2	SEMI_Staff_Report_121206
3	NA_&_TW_3DS-IC_Report_121206
4	Handling_&_Packaging_Materials_TF_Report_121206_(JA_only)
5	Electromagnetic_Characterization_SG_Report_121206_(JA_only)
6	P&PM_Eco-efficiency_TF_Report_121206_(JA_only)
7	Wafer_Shipping_Container_TF_Report_121206_(JA_only)
8	3D-IC_SG_Report_121206

#1 Due to file size and delivery issues, attachments must be downloaded separately. A .zip file containing all attachments for these minutes is available at www.semi.org. For additional information or to obtain individual attachments, please contact Naoko Tejima at the contact information above.